

SOT610-1

plastic thermal enhanced ball grid array package; 456 balls;
body 35 x 35 x 1.8 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA456
Package type industry code	HBGA456
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	14-8-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	34.8	-	35	35.2	mm
E	package width	34.8	-	35	35.2	mm
A	seated height	[tbd]	-	2.55	2.55	mm
A ₂	package height	1.6	-	1.8	1.85	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	456	-	



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2. Package outline

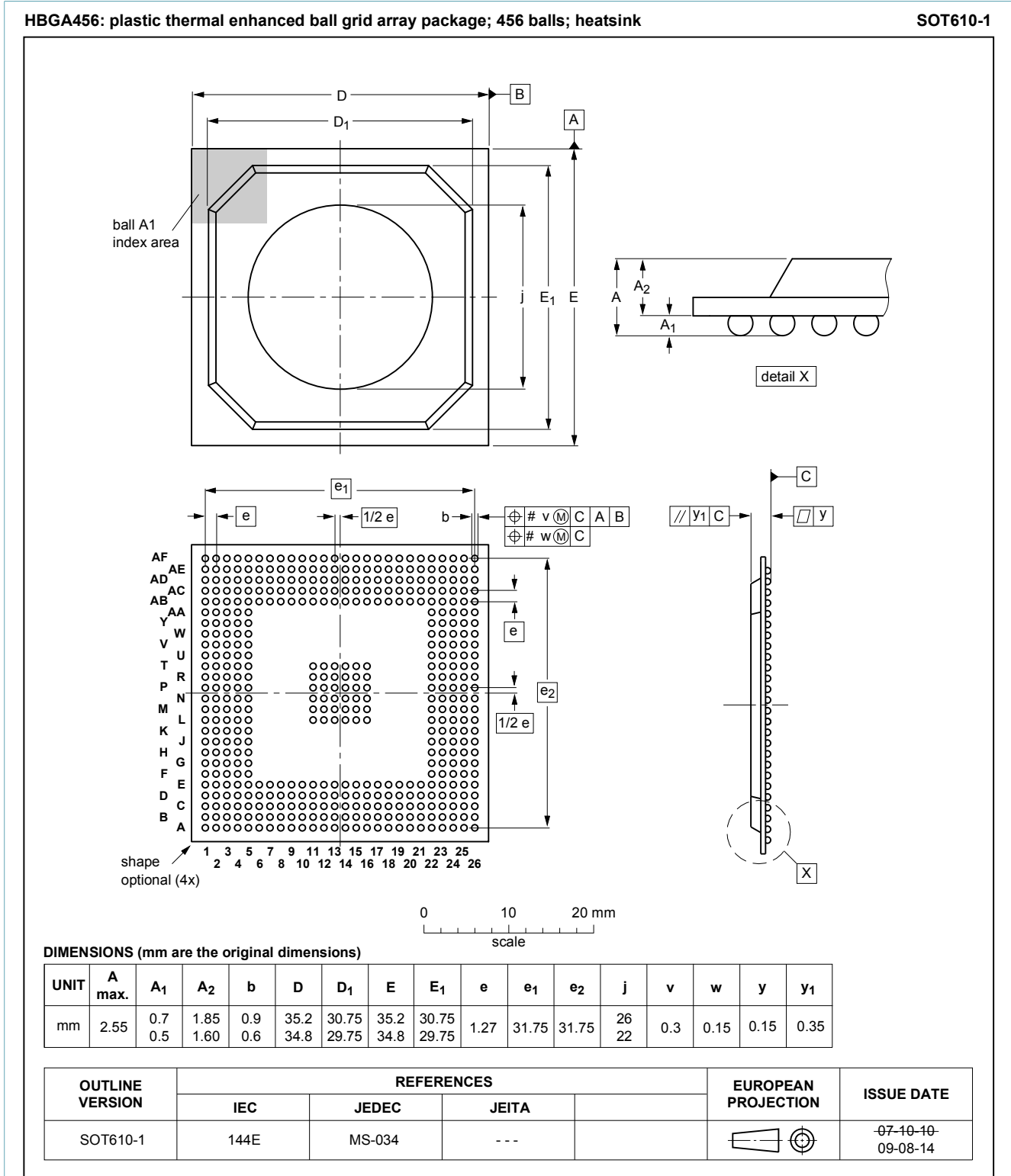


Fig. 1. Package outline HBGA456 (SOT610-1)

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3. Soldering

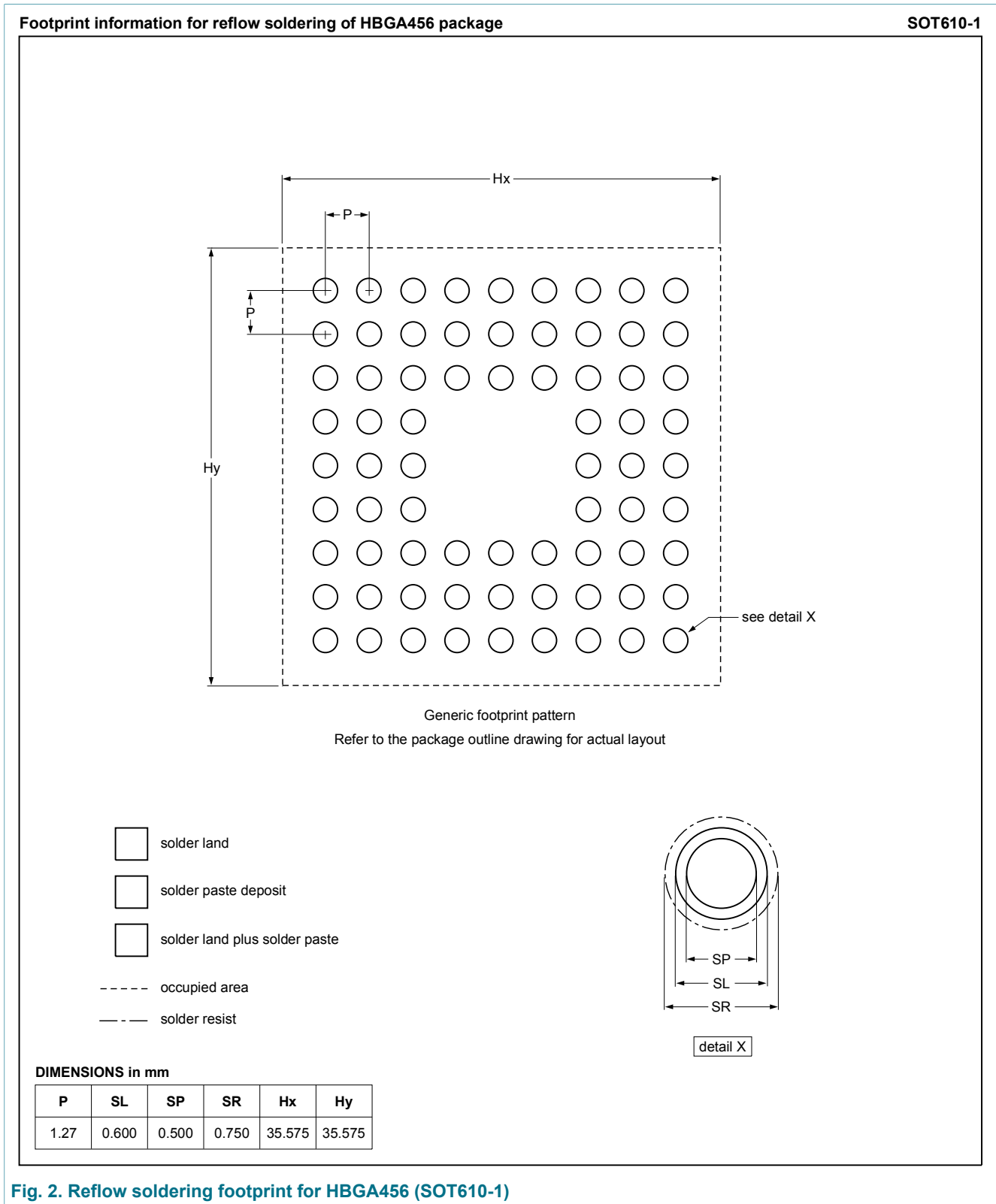


Fig. 2. Reflow soldering footprint for HBGA456 (SOT610-1)

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4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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